



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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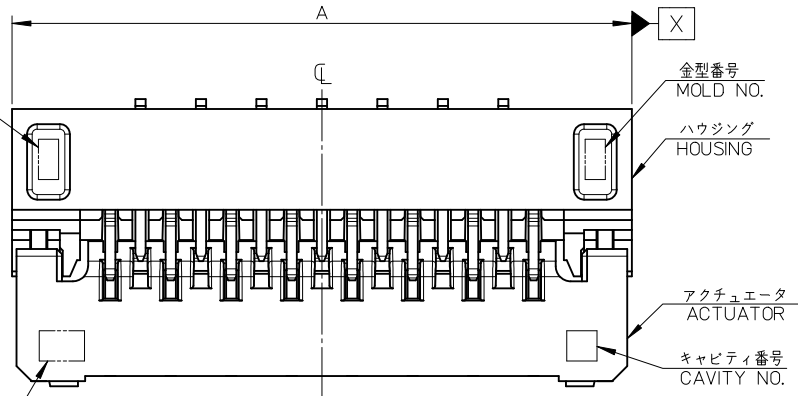
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

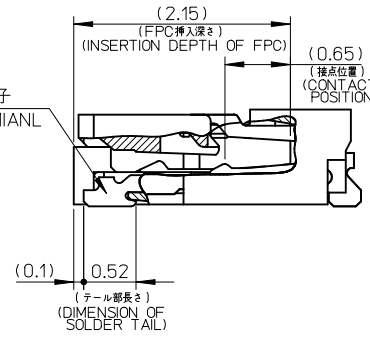


キャビティ番号  
CAVITY NO.

トレードマーク  
TRADE MARK

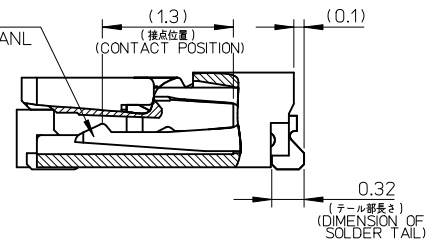


奇数極端子  
ODD TERMINAL

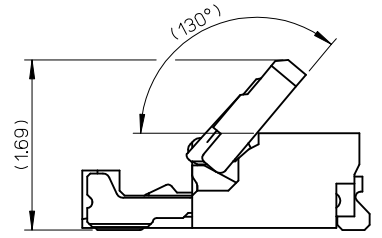
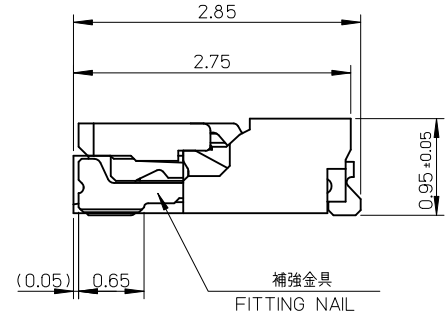
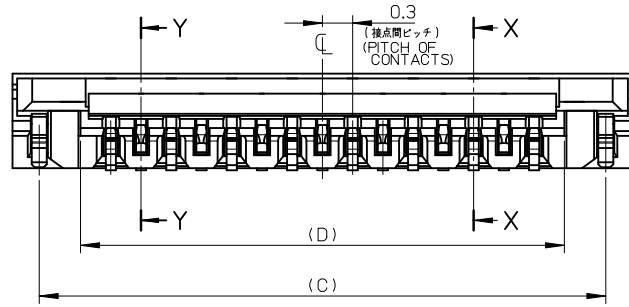


SECTION X-X

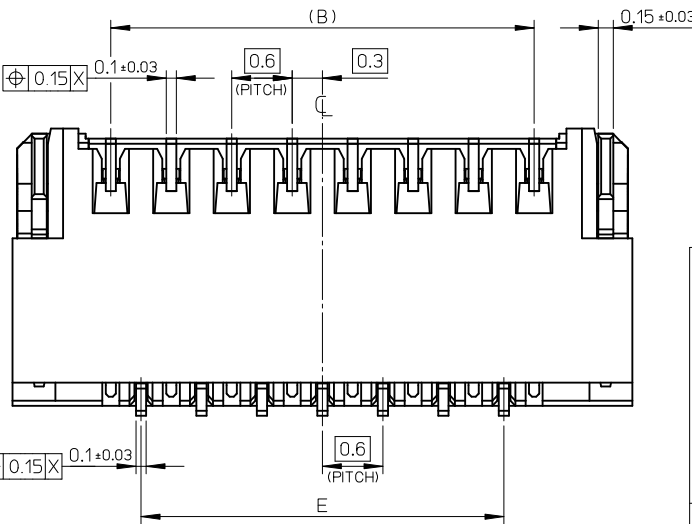
偶数極端子  
EVEN TERMINAL



SECTION Y-Y



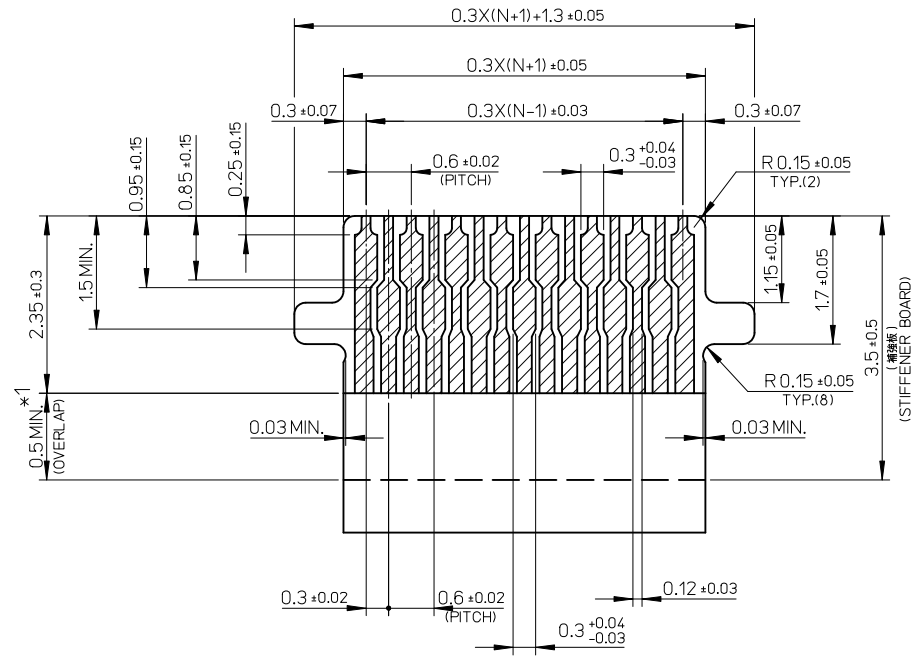
アクチュエータ開放位置  
POSITION OF ACTUATOR OPEN



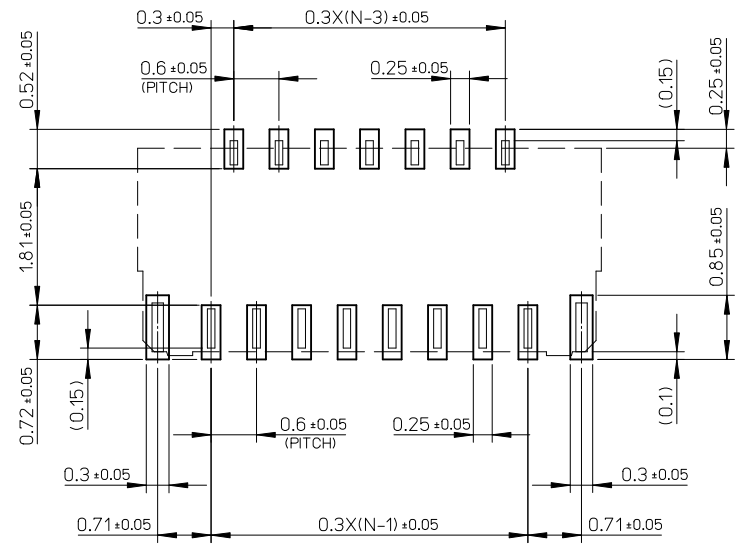
14.4	15.6	16.42	15.0	16.95	503566-5100	51
12.6	13.8	14.62	13.2	15.15	503566-4500	45
12.0	13.2	14.02	12.6	14.55	503566-4300	43
11.4	12.6	13.42	12.0	13.95	503566-4100	41
10.8	12.0	12.82	11.4	13.35	503566-3900	39
10.2	11.4	12.22	10.8	12.75	503566-3700	37
9.6	10.8	11.62	10.2	12.15	503566-3500	35
9.0	10.2	11.02	9.6	11.55	503566-3300	33
8.4	9.6	10.42	9.0	10.95	503566-3100	31
7.2	8.4	9.22	7.8	9.75	503566-2700	27
6.6	7.8	8.62	7.2	9.15	503566-2500	25
6.0	7.2	8.02	6.6	8.55	503566-2300	23
5.4	6.6	7.42	6.0	7.95	503566-2100	21
4.8	6.0	6.82	5.4	7.35	503566-1900	19
4.2	5.4	6.22	4.8	6.75	503566-1700	17
3.6	4.8	5.62	4.2	6.15	503566-1500	15
3.0	4.2	5.02	3.6	5.55	503566-1300	13
2.4	3.6	4.42	3.0	4.95	503566-1100	11
1.8	3.0	3.82	2.4	4.35	503566-0900	9
E	D	C	B	A	EMBOSSED PACKAGE	極数
					オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 503566-***8						

REVISED EC NO.: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: H IJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE _____		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY	DATE	TITLE						
	10 OVER 30 UNDER	± ---	CHECKED BY	DATE	0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM						
	30 OVER	± ---	APPROVED BY	DATE							
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 503566-***8		MOLEX INCORPORATED		DOCUMENT NO. SD-503566-001		SHEET NO. 1 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

補強板：ポリイミド  
STIFFENER BOARD: POLYIMIDE  
熱硬化接着剤  
THERMOSETTING ADHESIVE  
ベースフィルム：ポリイミド (25μm)  
BASE FILM: POLYIMIDE (25 μm)  
熱硬化接着剤  
THERMOSETTING ADHESIVE  
導体部：銅箔 (35μm)  
CONDUCTOR: COPPER FOIL (35 μm)  
熱硬化接着剤  
THERMOSETTING ADHESIVE  
カバーレイ：ポリイミド (25μm)  
COVER FILM: POLYIMIDE (25 μm)



適合するFPC推奨寸法 (参考)  
APPLICABLE FPC  
PATTERN DIMENSIONS(REF.)  
(端子部仕上がり厚さ: 0.2±0.03)  
(THICKNESS: 0.2±0.03)



参考基板レイアウト  
RECOMMENDED PCB  
PATTERN DIMENSIONS(REF.)

推奨ペースト厚 : 100μm  
推奨マスク開口率 : 80%  
RECOMMEND SCREEN THICKNESS : 100μm  
RECOMMEND SCREEN OPEN RATIO : 80%

注記 NOTES

- 使用材料 MATERIALS  
ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94V-0、ナチュラル (白色系)  
アクチュエータ: ポリアミド (PA)、ガラス充填、UL94V-HB、黒色  
奇数端子 : 燐青銅、ニッケル下地、金メッキ  
偶数端子 : 燐青銅、ニッケル下地、金メッキ  
補強金具 : 燐青銅、ニッケル下地、金メッキ  
HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED  
UL94V-0, NATURAL(WHITE)  
ACTUATOR : POLYAMIDE (PA), GLASS FILLED  
UL94V-HB, BLACK  
ODD TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING  
EVEN TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING  
FITTING NAIL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティは 0.1以下とする  
COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差 : ± 0.3  
GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

FPC構成推奨仕様  
STRUCTURE OF FPC

・FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します  
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します  
なお、接着剤の接点部への付着は導通不良の原因となりますので  
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE  
RECOMMENDED MATERIAL:  
STIFFENER BOARD: POLYIMIDE  
BONDING AGENT: THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様

金メッキ : 0.1μm 以上  
下地ニッケルメッキ : 2~6μm  
FPC PATTERN PLATING  
GOLD PLATING : 0.1μm MINIMUM  
NICKEL UNDER PLATING : 2~6μm

\*1 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください

WHEN STIFFENER BOARD DIMENSION CAN NOT  
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP  
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2	EC NO: J2011-1637	2011/05/31	DRW: N. H. YAMOTO	2011/05/31	CHK: D. H. J. J. IMA	2011/05/31	APP: R. K. MORIKAWA	2011/06/02
	GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE		SCALE	DESIGN UNITS
	10 UNDER ± ---				MM ONLY		---	METRIC
	10 OVER 30 UNDER ± ---				DRAWN BY H. I. J. IMA		DATE 2010/05/20	TITLE
30 OVER ± ---				CHECKED BY NMATSUURA		DATE 2010/05/20	0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM	
ANGULAR ±1 °				APPROVED BY KMORIKAWA		DATE 2010/06/11		MOLEX INCORPORATED
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
				503566-***8		SD-503566-001	2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

F

E

D

C

B

A

F

E

D

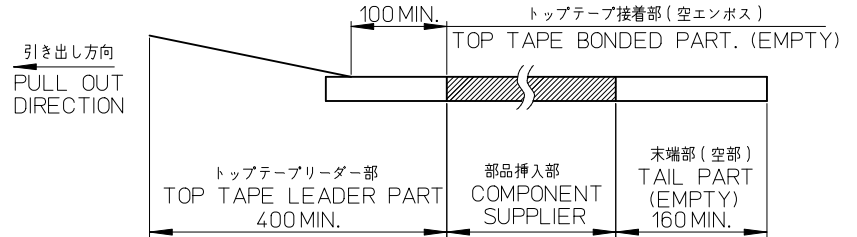
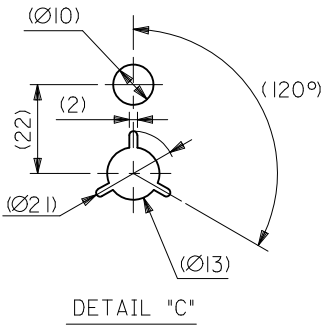
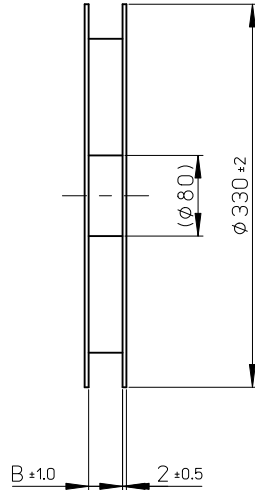
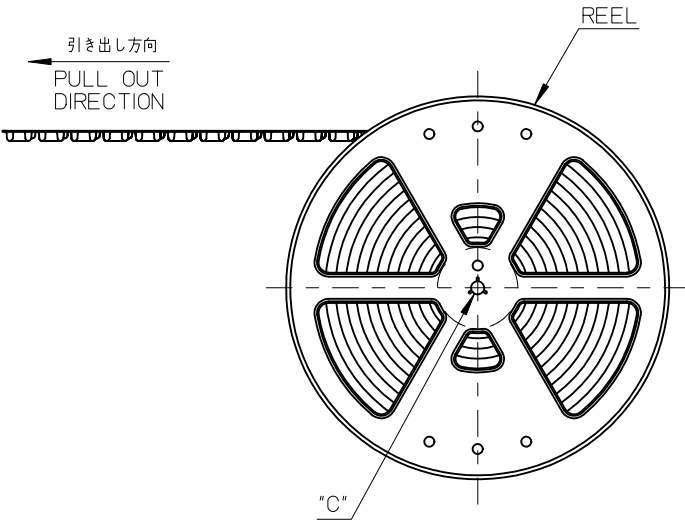
C

B

A

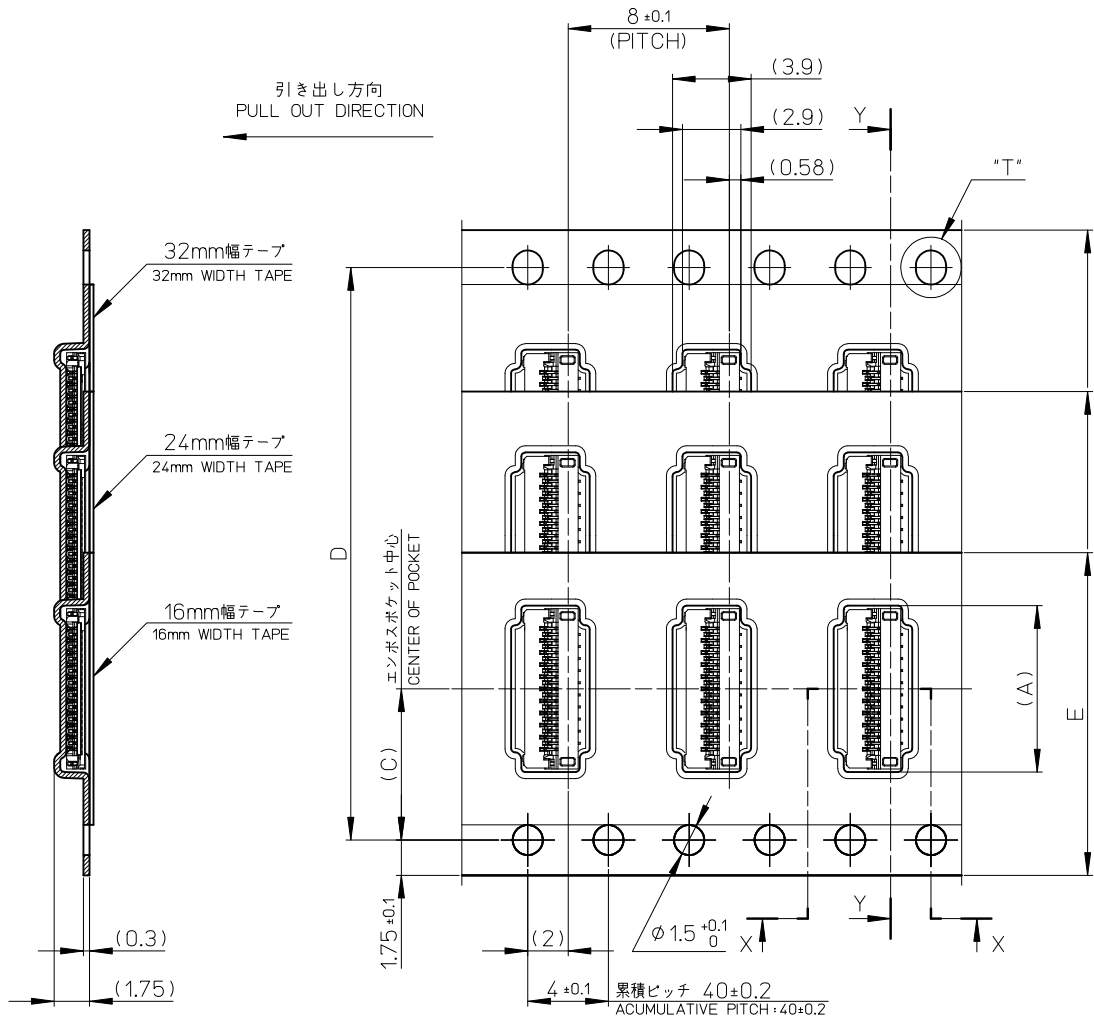
注記 NOTES

- 製品詳細寸法については図面 SD-503566-001 を参照下さい。  
RE DETAILED DIMENSION, SEE SD-503566-001
- 梱包数量：3000個/リール  
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

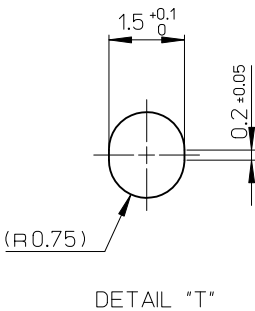


- 材料 MATERIAL  
 キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)  
 トップテープ (TOP TAPE) : PET , PE , PEF  
 リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>  
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剝離強度については、IEC60286-3に準拠  
 TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

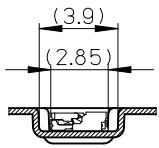
REVISED EC NO: J2011-1637 DRWN: HIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO.   503566-**00
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO.   SD-503566-002		
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.   SEE CHART		SHEET NO.   1 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



SECTION Y-Y



DETAIL "T"



SECTION X-X

32±0.3	28.4	14.2	33.4	17.25	503566-5100	51
24±0.3	—	11.5	25.4	15.45	503566-4500	45
				14.85	503566-4300	43
				14.25	503566-4100	41
				13.65	503566-3900	39
				13.05	503566-3700	37
				12.45	503566-3500	35
				11.85	503566-3300	33
				11.25	503566-3100	31
				10.05	503566-2700	27
				16±0.3	—	7.5
8.85	503566-2300	23				
8.25	503566-2100	21				
7.65	503566-1900	19				
7.05	503566-1700	17				
6.45	503566-1500	15				
5.85	503566-1300	13				
5.25	503566-1100	11				
4.65	503566-0900	9				
E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002		
	ANGULAR ±3 °		MATERIAL NO.		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							